

ABSTRACT OF DISCLOSURE

A flip chip semiconductor device has a cell forming layer assigned to macro-cells and input and output cells and a pad forming layer assigned to power supply pads for the macro-cells and input and output cells and signal pads for the input and output cells, and the signal pads are arranged outside of the power supply pads, whereby a package substrate to be assembled with the flip chip semiconductor device is simplified by virtue of the signal lines on a level with the signal pads, because any power supply pad is not an obstacle against the signal lines.